

IN THE CLAIMS

Please amend the claims to read as follows:

1 1. (Twice Amended) A method of marking an electronic integrated circuit chip having surfaces
2 comprising the following steps:
C1 3 forming internal marking indicia on a marking location upon an exterior surface of the chip for
4 identification of the chip, and
5 forming a non-black, optically transmissive encapsulating material over at least the marking
6 location on the one exterior surface of the chip which non-black, optically transmissive material
7 cannot be scraped off of the chip for prevention of replacement of the internal marking indicia by
8 different markings.

C2 3 3. (Twice Amended) The method of claim 1 wherein the non-black, optically transmissive
encapsulating material is a protective encapsulating material adapted to provide protection from
damage as the result of environmental and handling factors.

C3 3 6. (Twice Amended) The method of claim 1 wherein the non-black, optically transmissive material
comprises a material such as epoxy which prevents remarking indicia or identification marks on the
chip.

1 12. (Thrice Amended) A method of marking an electronic integrated circuit chip having surfaces
C4 2 comprising:
3 forming internal marking indicia on a marking location upon an exterior surface of the chip, and
4 forming a non-black, optically transparent material colored with a particular color over at
5 least the marking location on that exterior surface of the chip wherein the material colored with
6 the particular color together with the marking indicia represents identification of the chip which
7 non-black, optically transparent, colored material cannot be scraped off of the chip for prevention of
8 replacement of the internal marking indicia by different markings.

C4
Cone 10

1 13. (Thrice Amended) An electronic integrated circuit chip comprising:
2 the chip having exterior surfaces,
3 internal marking indicia formed on a marking location upon an exterior surface
4 of the chip for identification of the chip, and
5 a non-black, optically transmissive material formed over at least the marking location on the one
6 exterior surface of the chip which non-black, optically transmissive material cannot be easily scraped
7 off for prevention of replacement of the internal marking indicia by different markings.

C5

1 22. (Twice Amended) An electronic integrated circuit chip comprising:
2 a semiconductor, integrated circuit chip having surfaces including a planar front surface, a
3 planar back surface and edges of the chip between the planar surfaces with at least one electrical
4 contact site on a surface,
5 indicia marked upon an exterior marking portion of a surface of the chip for identification of the
6 chip,
7 a non-black layer covering the exterior surface of the chip at least at the exterior marking
8 portion thereof, the non-black layer being composed of a colored, optically transmissive material
9 which non-black, optically transmissive material cannot be scraped off of the chip for prevention of
10 replacement of the indicia by different markings and for preventing remarking the indicia on the
11 exterior marking surface of the chip, and
12 the indicia being visible through the non-black layer.

C6

1 25. (Thrice Amended) An electronic integrated circuit chip comprising:
2 internal marking indicia formed on a marking location upon an exterior surface of the chip, and
3 a non-black, optically transparent material colored with a particular color formed over at least
4 the marking location on that exterior surface of the chip wherein the material colored with the
5 particular color together with the marking indicia represents identification of the chip which
6 non-black, optically transmissive material cannot be scraped off of the chip for prevention of
7 replacement of the internal marking indicia by different markings.
